**Preferred Device** 

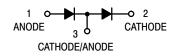
# **Dual Switching Diode**

### **Features**

• Pb-Free Packages are Available



http://onsemi.com





SOT-23 (TO-236AB) CASE 318-08 STYLE 8

## MAXIMUM RATINGS (EACH DIODE)

Rating	Symbol	Value	Unit
Reverse Voltage	V <sub>R</sub>	100	Vdc
Forward Current	I <sub>F</sub>	200	mAdc
Peak Forward Surge Current	I <sub>FM(surge)</sub>	500	mAdc

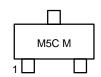
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit	
Total Device Dissipation FR-5 Board (Note 1)T <sub>A</sub> = 25°C	P <sub>D</sub>	225	mW	
Derate above 25°C		1.8	mW/°C	
Thermal Resistance, Junction to Ambient	$R_{ heta JA}$	556	°C/W	
Total Device Dissipation Alumina Substrate, (Note 2) T <sub>A</sub> = 25°C	P <sub>D</sub>	300	mW	
Derate above 25°C		2.4	mW/°C	
Thermal Resistance, Junction–to–Ambient	$R_{\theta JA}$	417	°C/W	
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	

- 1. FR-5 =  $1.0 \times 0.75 \times 0.062$  in.
- 2. Alumina =  $0.4 \times 0.3 \times 0.024$  in. 99.5% alumina.

### **MARKING DIAGRAM**



M5C = Specific Device Code

M = Date Code

■ = Pb-Free Package

### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMBD7000LT1	SOT-23	3000 Tape & Reel
MMBD7000LT1G	SOT-23 (Pb-Free)	3000 Tape & Reel
MMBD7000LT3	SOT-23	10,000 Tape & Reel
MMBD7000LT3G	SOT-23 (Pb-Free)	10,000 Tape & Reel

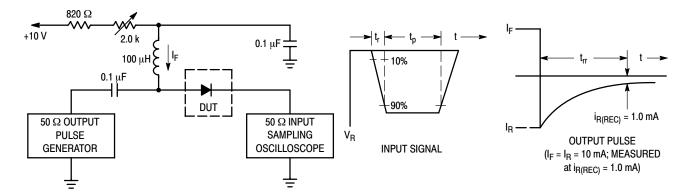
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

**Preferred** devices are recommended choices for future use and best overall value.

Downloaded from Arrow.com.

### **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted) **(EACH DIODE)**

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS	<u>.</u>			
Reverse Breakdown Voltage (I <sub>(BR)</sub> = 100 μAdc)	V <sub>(BR)</sub>	100	_	Vdc
Reverse Voltage Leakage Current $(V_R = 50 \text{ Vdc})$ $(V_R = 100 \text{ Vdc})$ $(V_R = 50 \text{ Vdc}, 125^{\circ}\text{C})$	I <sub>R</sub> I <sub>R2</sub> I <sub>R3</sub>	- - -	1.0 3.0 100	μAdc
Forward Voltage $(I_F = 1.0 \text{ mAdc})$ $(I_F = 10 \text{ mAdc})$ $(I_F = 100 \text{ mAdc})$	V <sub>F</sub>	0.55 0.67 0.75	0.7 0.82 1.1	Vdc
Reverse Recovery Time (I <sub>F</sub> = I <sub>R</sub> = 10 mAdc) (Figure 1)	t <sub>rr</sub>	-	4.0	ns
Capacitance (V <sub>R</sub> = 0 V)	С	_	1.5	pF



Notes: 1. A 2.0 k $\Omega$  variable resistor adjusted for a Forward Current (I<sub>F</sub>) of 10 mA.

- 2. Input pulse is adjusted so  $I_{R(peak)}$  is equal to 10 mA.
- 3. t<sub>p</sub> » t<sub>rr</sub>

Figure 1. Recovery Time Equivalent Test Circuit

### **CURVES APPLICABLE TO EACH DIODE**

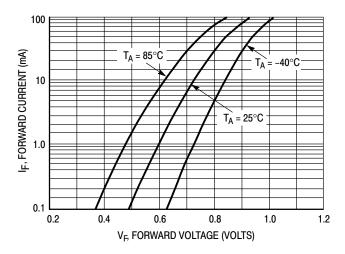


Figure 2. Forward Voltage

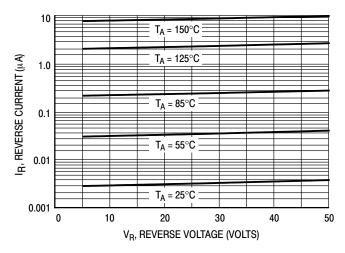


Figure 3. Leakage Current

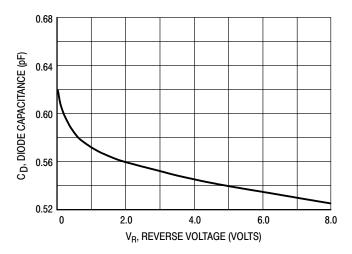
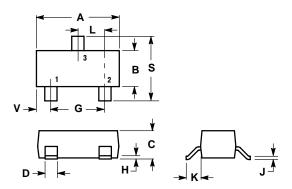


Figure 4. Capacitance

### PACKAGE DIMENSIONS

SOT-23 (TO-236AB) CASE 318-08 **ISSUE AH** 



#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF
- BASE MATERIAL. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.

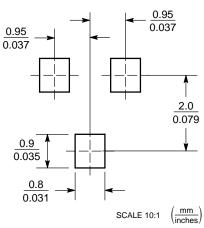
	INCHES		S MILLIM	
DIM	MIN	MAX	MIN	MAX
Α	0.1102	0.1197	2.80	3.04
В	0.0472	0.0551	1.20	1.40
С	0.0350	0.0440	0.89	1.11
D	0.0150	0.0200	0.37	0.50
G	0.0701	0.0807	1.78	2.04
Н	0.0005	0.0040	0.013	0.100
J	0.0034	0.0070	0.085	0.177
K	0.0140	0.0285	0.35	0.69
L	0.0350	0.0401	0.89	1.02
S	0.0830	0.1039	2.10	2.64
V	0.0177	0.0236	0.45	0.60

#### STYLE 8:

PIN 1. ANODE

- NO CONNECTION
- CATHODE

### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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